



Simulation, Numerical Calculation and Energy Transport of Nanofluids

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

Nanomaterials are at the heart of nanotechnology, crystal engineering, thermal engineering, material science, and physics. They improve the heating phenomenon, control crystal bonding, and comprise layered materials. Experimentally supported research proves that the interaction of different types of nanoparticles is more effective to enhance the thermal transportation phenomenon. It has been commonly observed that mathematical modelling of nanofluid problems results in complex non-linear differential equations. Various numerical techniques have been implemented to compute the simulation of such problems.

Dr. Sami Ullah Khan
Guest Editor





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Message from the Editor-in-Chief

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